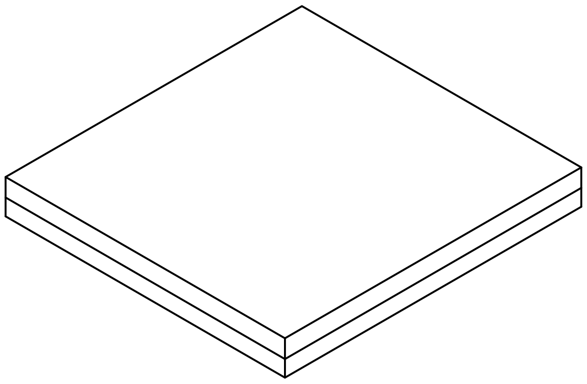
REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN C04816	10/12/98	E.B.	HLE



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6 PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5 DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 144.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 12 X 12.

2. THE BASIC SOLDER BALL GRID PITCH IS 1.00.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETERS
DECIMAL ANGULAR
X.X ±0.10 ±1°
X.XX ±0.05
X.XXX ±0.03

MATERIAL N/A

FINISH N/A

DO NOT SCALE DRAWING

PROJECTION

APPROVALS		DATE
DRAWN	HOAI LE	10/02/98
CHECKED	M. EMMETTE	10/02/98
ENG'R	T. PANCZAK	10/02/98
RELEASED	M. ANTONIO	10/12/98

ANAM Industrial Co., LTD.
Sungdong-Ku, Seoul, Korea

AMKOR Electronics, Inc.
Chandler, Arizona, USA

amkor
anam

TITLE
PACKAGE OUTLINE – CABGA 144,
13.00mm X 13.00mm, 2 LAYER,
1.00mm PITCH, LAMINATE SUBSTRATE, AAP

SIZE	SID NUMBER	DWG NUMBER	REV
B	N/A	74529	00

STRIP DWG NUMBER/REV	CUST CODE		
N/A	N/A	SCALE: 8:1	SHEET 1 OF 3